

G4L4-AD3-LAX7

HPC/AI Server - Intel® Xeon® 6900E+/6900-Series Processors - 4U, DP, NVIDIA HGX™ B300, DLC



Key Features

- Liquid-cooled NVIDIA HGX™ B300
- Integrated-manifold DLC solution with leak detection
- 8 x 800 Gb/s OSFP XDR InfiniBand or dual 400 Gb/s Ethernet GPU networking ports via onboard NVIDIA ConnectX® -8 SuperNIC™
- 1.8 TB/s GPU-to-GPU bandwidth with NVIDIA NVLink™
- Dual Intel® Xeon® 6900E+/6900-series processors
- 12-Channel DDR5 RDIMM/MRDIMM per CPU with 24 x DIMMs
- Compatible with NVIDIA BlueField® -3 DPUs
- 2 x 10 Gb/s LAN ports via Intel® X710-AT2
- 2 x M.2 slots with PCIe Gen5 x4 and x2
- 8 x 2.5" Gen5 NVMe hot-swap bays
- 4 x FHHL PCIe x16 slots with Gen5 x16 lanes
- 5+5 3000 W 80 PLUS Titanium redundant power supplies

Specification

Dimensions	4U (W447 x H175.5 x D901 mm)	Modular GPU	[DLC] NVIDIA HGX™ B300 with 8 x SXM GPUs
Motherboard	MAB4-PE3	PCIe Expansion Slots	4 x FHHL x16 (Gen5 x16)
CPU	Intel® Xeon® 6+ processors - Intel® Xeon® 6900E+ processors - Intel® Xeon® 6 processors - Intel® Xeon® 6900-series processors [DLC] Dual processors, TDP up to 500 W	I/O Ports	Front: 2 x USB 3.2 Gen1, 1 x VGA, 2 x RJ45, 1 x MLAN Rear: MLAN board:, 1 x MLAN
OS Compatibility	OS Support List	TPM	1 x TPM header (SPI), Optional TPM 2.0 kit: CTM012
Socket	2 x LGA 7529 (Socket BR)	Power Supply	5+5 3000 W 80 PLUS Titanium redundant power supplies AC Input: 115-240 V *The system power supply requires C19 power cord.
Chipset	Integrated into SoC	System Fans	Motherboard: 2 x 60x60x38mm 3 x 60x60x56mm PCIe slots: 2 x 80x80x56mm
Memory	12-Channel DDR5 RDIMM/MRDIMM, 24 x DIMMs Intel Xeon 6900E+: [RDIMM] Up to 8000 MT/s Intel Xeon 6900-series [RDIMM] Up to 6400 MT/s [MRDIMM] Up to 8800 MT/s ^[1] MRDIMMs are supported only on select Intel® Xeon® 6 processors with P-cores.	Operating Properties	Operating: 10°C to 35°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing) *To ensure system stability and prevent condensation, when the relative humidity exceeds 50%, the coolant inlet temperature must be higher than the dry-bulb temperature and it should not exceed 45°C.
LAN	Front: 2 x 10 Gb/s LAN (1 x Intel® X710-AT2), Support NCSI 1 x 10/100/1000 Mb/s Management LAN Rear: [DLC] 8 x 800 Gb/s OSFP XDR InfiniBand or dual 400 Gb/s Ethernet, for GPU networking 1 x 10/100/1000 Mb/s Management LAN	Packaging Content	1 x G4L4-AD3-LAX7 2 x CPU carriers 1 x L-shape Rail kit
Video	Integrated in ASPEED® AST2600 - 1 x VGA port	Ordering Part Numbers	6NG4L4AD3DR000LAX7*
Storage	Front hot-swap: 8 x 2.5" Gen5 NVMe Internal M.2: 1 x M.2 (2280/22110), PCIe Gen5 x4 1 x M.2 (2280/22110), PCIe Gen5 x2		



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